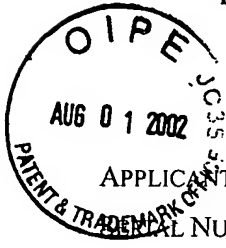


Express Mail Label No. ET38110526US

Date of Deposit: August 1, 2002

Attorney Docket No. 23905-029

#9/C
8-8-02
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANTS: Soutar and McGrath

SERIAL NUMBER: 10/099,936

EXAMINER: Not Yet Assigned

FILING DATE: March 13, 2002

ART UNIT: 1762

FOR: PRINTED CIRCUIT BOARD MANUFACTURE

August 1, 2002
Boston, Massachusetts

Commissioner for Patents
Washington, D.C. 20231

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SECOND PRELIMINARY AMENDMENT

Applicants submit herewith a Second Preliminary Amendment for the above-identified patent application. Applicants believe that no fee is required for the filing of the present paper. However, the Commissioner is hereby authorized to charge any fees that may be due, or credit any overpayment of same, to Deposit Account No. 50-0311, Reference No. 23905-029.

AMENDMENTS UNDER 37 C.F.R. §1.115

In the Claims:

Please add the following new claims:

32. A process for improving the solderability of a metal surface, said process comprising:
- a). contacting the metal surface with an immersion silver plating solution thereby producing an immersion silver plate upon the metal surface; and thereafter
 - b). treating the immersion silver plated metal surface with a solution comprising an additive selected from the group consisting of fatty amines, fatty amides, quaternary salts, and ethoxylated versions of any of the foregoing.

33. A process according to claim 32 wherein the silver plating solution comprises a material selected from the group consisting of imidazoles, benzimidazoles, imidazole derivatives and benzimidazole derivatives.